

GDP (GETTERING DRY POLISHING PAD)

EHWA Gettering Dry Polishing Pad Test Processed Material

- **Silicon Wafer** : 12inch
- **BG tape type** : AMC APB1-330
- **Machine** : Disco DGP8761
- **Quantity** : Dummy wafer x10 pcs

Wheel Type

- **Z1** : EHWA Back Grinding Wheel
- **Z2** : EHWA Back Grinding Wheel
- **Z3** : EHWA-Gettering Polishing Pad

